PCN Number:		20130403002				PCN D	ate:	07/25/2013			
Title: Die Revision PG3.0 for AM387x/DM812x/DM814x Devices											
Customer Contact:		PCN	PCN Manager		P	hone:	+1(214)480-6037		Dept:	Qua	lity Services
Proposed 1 st Ship Date:		te:	10	.0/25/2013 Estimated Sample Avail			ilability:		provided at ole request.		
Change Type:											
Assembly Site			Assembly Process			Assembly	Assembly Materials				
Design			☐ Electrical Specification ☐ N			Mechanica	Mechanical Specification				
Test Site				Packing/Shipping/Labeling T			Test Process				
Wafer Bump Site		e		☐ Wafer Bump Material ☐ V			Wafer Bump Process				
Wafer Fab Site				☐ Wafer Fab Materials ☐ \			Wafer Fab Process				
PCN Details											

Description of Change:

This is a resend of a previous document to add Sitara Device table which was inadvertently left out.

The purpose of this notification is to introduce die revision PG3.0 for AM387x/DM812x/DM814x devices.

Affected devices are listed in Product Affected section.

Change from revision PG2.1 to revision PG3.0 will not require customer hardware or software upgrades.

Current Rev	New Rev	HW SW Change Requirements		
PG2.1 (Rev B)	PG3.0 (Rev C)	Direct replacement, no requirements		

As part of this change, the orderable part numbers will be changing. The table below shows part number mapping.

DaVinci Video Devices

	Previous Rev (Map From)	PG 3.0 Part N	PG 3.0 Part Number (Map To)		
P/N	PG 2.1	Video Surveillance Applications	- Non-Video Surveillance - Broad Market Applications		
DM8147	TMS320DM8147BCYE0	TMS320DM8147SCYE0			
	TMS320DM8147BCYE1	TMS320DM8147SCYE1			
	TMS320DM8147BCYE2	TMS320DM8147SCYE2			
DM8148	TMS320DM8148BCYE0	TMS320DM8148SCYE0	TMS320DM8148CCYE0		
	TMS320DM8148BCYE1	TMS320DM8148SCYE1	TMS320DM8148CCYE1		
	TMS320DM8148BCYE2	TMS320DM8148SCYE2	TMS320DM8148CCYE2		

(additional product tables on next page)

Sitara Devices

	Previous Rev (Map From)	PG 3.0 Part Number (Map To)		
P/N	PG 2.1	Video Surveillance Applications	- Non-Video Surveillance - Broad Market Applications	
AM3874	AM3874BCYE80	AM3874CCYE80		
	AM3874BCYEA80	AM3874CCYEA80		
AM3871	AM3871BCYE80	AM3871CCYE80		
	AM3871BCYE100	AM3871CCYE100		

Video Security Devices:

	Previous Rev (Map From)	PG 3.0 Part N	PG 3.0 Part Number (Map To)		
P/N	PG 2.1	Video Surveillance Applications	- Non-Video Surveillance - Broad Market Applications		
	TMS320DM8127BCYE0	TMS320DM8127SCYE0			
	TMS320DM8127BCYE1	TMS320DM8127SCYE1			
	TMS320DM8127BCYE2	TMS320DM8127SCYE2			
DM8127	TMS320DM8127BCYE3	TMS320DM8127SCYE3			
	TMS320DM8127BCYED0	TMS320DM8127SCYED0			
	TMS320DM8127BCYED1	TMS320DM8127SCYED1			
	TMS320DM8127BCYED2	TMS320DM8127SCYED2			
	TMS320DM8127BCYED3	TMS320DM8127SCYED3			
	TMS320DM8127BCYEA3	TMS320DM8127SCYEA3			

The table below lists PG3.0 design changes.

Issue	Resolution		
SATA: Unable to Operate Both SATA and	Resolves Advisory 2.1.27		
SATA: Gen3 Link Establishment Fails	Resolves Advisory 2.1.28		
HDVPSS CCS Lockup	Resolves Advisory 2.1.51		
HDVPSS: Connect/Disconnect Lockup	Resolves Advisory 2.1.59		
DDR DMM: Starvation	Resolves Advisory 2.1.68		
Input Receiver is Disabled	Resolves Advisory 2.1.87		

No datasheet changes are required.

Availability of PG2.1:

- After release of the change and shipment of the remaining PG2.1 inventory, the PG2.1 (revB) part numbers listed in this document will become obsolete.
- We recommend that customers add the revision PG3.0 (revC) part numbers to their product bill of materials (BOM) and keep the revision PG2.1 part numbers on the BOM until the 2.1 inventory is depleted.

June 30th 2014 will be the last order entry date. December 31st 2014 will be the last shipment date.

Reason for Change:

Advisory Resolution. PG3.0 is intended as the long term production device for all customers and applications.

Anticipated impact on Fit, Form, Function & Reliability (positive / negative):

No impact

Changes to product identification resulting from this PCN:

Die Rev designator will change as shown in table & sample label below:

Current	New		
Die Rev [2P]	Die Rev [2P]		
В	C		

Sample product shipping label to indicate die rev location (not actual product label)



Product Affected:

AM3871BCYE100	TMS320DM8127BCYE1	TMS320DM8127BCYED1	TMS320DM8147BCYE2
AM3871BCYE80	TMS320DM8127BCYE2	TMS320DM8127BCYED2	TMS320DM8148BCYE0
AM3874BCYE80	TMS320DM8127BCYE3	TMS320DM8127BCYED3	TMS320DM8148BCYE1
AM3874BCYEA80	TMS320DM8127BCYEA3	TMS320DM8147BCYE0	TMS320DM8148BCYE2
TMS320DM8127BCYE0	TMS320DM8127BCYED0	TMS320DM8147BCYE1	

Qualification Data: Approved 10/22/2012 This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications. **Qualification Device: XDM8148CYE** Wafer Fab Site: UMC 12A Assembly Site: AMK-K4 Wafer Fab Process: CMOS # Pins-Designator, Family: 684-CYE, FCBGA Die Revision: C **Qualification: ☐** Plan **Test Results** Sample Size Reliability Test Conditions Lot#1 **Electrical Characterization** Pass 168 hours @ 125C 111/0 EFR/HTOL +/- 100 ma, 1.5 x Vcc @ 105C Latch-up 6/0 ESD HBM +/- 1000V 5/0 ESD CDM +/- 250V 5/0

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com